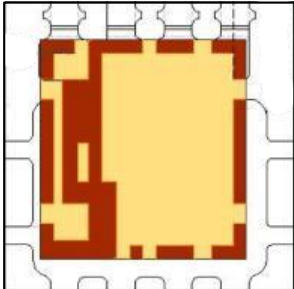
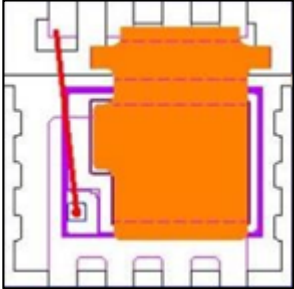




Title of Change:	Update to FPCN22253X - PQFN_33CLP Metal Clip with Cu Gate Wire Conversion	
Proposed first ship date:	15 July 2019	
Contact information:	Contact your local ON Semiconductor Sales Office or < Joseph.Mendoza@onsemi.com >	
Samples:	Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < KarenMae.Taping@onsemi.com >.	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com >	
Change Part Identification:	Affected products will be identified with date code	
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input checked="" type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: ON Cebu, Philippines	External Foundry/Subcon Sites: None
Description and Purpose:		
<p>FPCN22253X was previously released to announce the conversion of PQFN_33CLP from using Pre-Molded Clip to Metal Clip with Cu Gate wire to improve Gate leadpost interconnection.</p> <p>This Update Notification announces the following:</p> <ol style="list-style-type: none"> 1. Corrected typo error on bare metal clip thickness under the "After Change Description" column from 0.508mm thick to 0.254mm thick, as shown in the table. 2. Updated information on Reliability Data Summary table. 3. Updated proposed first ship date from July 20, 2018 to July 15, 2019. 		
	Before Change Description	After Change Description
Clipframe	Pre-molded Clip (0.254mm thick) 	Bare Metal Clip (0.254mm thick) with 2mil Cu Gate Wire 



Reliability Data Summary:

QV DEVICE NAME: FDMC7570S

RMS: F43951

PACKAGE: PQFN_33CLP

Test	Specification	Condition	Interval	Results
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Part Number	Qualification Vehicle
FDMC7570S	FDMC7570S
FDMC7660S	FDMC7570S



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
FDMC7570S		FDMC7570S
FDMC7660S		FDMC7570S